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DS16F95A TIA/EIA-485-A (RS-485) Extended Temperature Differential Bus Transceiver

Check for Samples: [DS16F95A](#)

FEATURES

- Extended Temperature Range to +180 °C
- Conforms to TIA/EIA-485-A
- Designed for Multipoint Transmission
- Wide Positive and Negative I/O Bus Voltage Range
- Driver Positive and Negative Current-Limiting
- High Impedance Receiver Input
- Receiver Input Hysteresis of 50 mV Typical
- Operates from Single 5.0V Supply
- Reduced Power Consumption
- Pin Compatible with DS16F95/DS3695 and SN75176A
- Available in a 8-Lead CDIP Package

DESCRIPTION

The DS16F95A Differential Bus Transceiver is a monolithic integrated circuit designed for bidirectional data communication on balanced multipoint bus transmission lines. The transceiver conforms to both TIA/EIA-485-A and TIA/EIA-422-B standards.

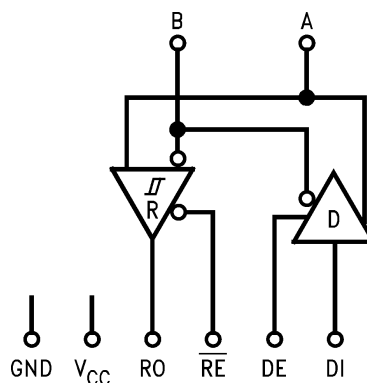
The DS16F95A offers improved performance due to the use of L-FAST bipolar technology. The L-FAST technology allows for higher speeds and lower currents by minimizing gate delay times. The DS16F95A features an extended temperature range and is offered in a rugged ceramic package.

The DS16F95A combines a TRI-STATE differential line driver and a differential input line receiver, both of which operate from a single 5.0V power supply. The driver and receiver have an active Enable that can be externally connected to function as a direction control. The driver differential outputs and the receiver differential inputs are internally connected to form differential input/output (I/O) bus ports that are designed to offer minimum loading to the bus whenever the driver is disabled or when $V_{CC} = 0V$. These ports feature wide positive and negative common mode voltage ranges, making the device suitable for multipoint applications in noisy environments.

The driver is designed to accommodate loads of up to 60 mA of sink or source current and features positive and negative current limiting for protection from line fault conditions.

The device is offered in a rugged 8-lead CDIP package and is functional over the extended temperature range of -55 °C to +180 °C.

LOGIC DIAGRAM



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

DS16F95A

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FUNCTION TABLES
Table 1. DRIVER

Driver Input	Enable	Outputs	
DI	DE	A	B
H	H	H	L
L	H	L	H
X	L	Z	Z

Table 2. Receiver

Differential Inputs	Enable	Output
A–B	\overline{RE}	RO
$V_{ID} \geq 0.2V$	L	H
$V_{ID} \leq -0.2V$	L	L
$0.2V > V_{ID} > -0.2V$	L	X
X	H	Z



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾⁽²⁾

Storage Temperature Range ⁽³⁾	-65°C to +175°C
Lead Temperature (Soldering, 60 sec.)	300°C
Junction Temperature	+200°C
Maximum Package Power Dissipation Capacity (J)	1300 mW
Above 25°C, derate J package	8.7 mW/°C
Supply Voltage	7.0V
Input Voltage (Bus Terminal)	+15V/-10V
Enable Input Voltage	5.5V
ESD Ratings	See ⁽⁴⁾

- (1) "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be verified. They are not meant to imply that the devices should be operated at these limits. The tables of "Electrical Characteristics" provide conditions for actual device operation.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales office/Distributor for availability and specifications.
- (3) Lifetime expectations for continuous operation at above 150 °C for more than 1000 hours should be verified with Texas Instruments Reliability Engineering. Reliability report available upon request.
- (4) ESD Rating information: HBM >5kV A or B pin, all other pins > 1kV. MM > 600V A or B pin, all other pins > 50V, CDM >750V, IEC61000-4-2 (Power On or Off) > 2kV A or B pin.

Recommended Operating Conditions⁽¹⁾

	Min	Typ	Max	Units
Supply Voltage (V_{CC})	4.50	5.0	5.50	V
Voltage at Any Bus Terminal (Separately or Common Mode)				
	(V_I or V_{CM})	-7.0	+12	V
Differential Input Voltage (V_{ID})			±12	V
Output Current HIGH (I_{OH})	Driver		-60	mA
	Receiver		-400	µA
Output Current LOW (I_{OL})	Driver		60	mA
	Receiver		2	mA
Operating Temperature (T_A)	-55	+25	+180	°C

- (1) Lifetime expectations for continuous operation at above 150 °C for more than 1000 hours should be verified with Texas Instruments Reliability Engineering. Reliability report available upon request.

Driver Electrical Characteristics⁽¹⁾⁽²⁾

Over recommended supply voltage and operating temperature ranges, unless otherwise specified.

Parameter		Test Conditions		Min	Typ	Max	Units
V _{IH}	Input Voltage HIGH	DI, DE		2.0			V
V _{IL}	Input Voltage LOW					0.8	V
V _{IC}	Input Clamp Voltage		I _I = -18 mA			-1.3	V
I _{IH}	Input Current HIGH		V _I = 2.4V			20	μA
I _{IL}	Input Current Low		V _I = 0.4V			-50	μA
V _{OD1}	Differential Output Voltage	A-B, Figure 1	I _O = 0 mA, No Load		3.6	6.0	V
V _{OD2}	Differential Output Voltage		R _L = 100Ω	2.0	2.9		V
Δ V _{OD}	Change in Magnitude of Differential Output Voltage		R _L = 54Ω	1.5	2.6		V
V _{OC}	Common Mode Output Voltage ⁽⁴⁾	(A+B)/2, Figure 1			2.5	3.0	V
Δ V _{OC}	Change in Magnitude of Common Mode Output Voltage ⁽³⁾					±0.2	V
I _O	Output Current ⁽⁵⁾ (Includes Receiver I _I)	A or B, Output Disabled, DE = 0.4V	V _O = +12V		0.57	1.5	mA
			V _O = -7.0V		-0.43	-0.8	
I _{OS}	Short Circuit Output Current ⁽⁶⁾	A or B	V _O = -7.0V		-157	-250	mA
			V _O = 0V		-115	-150	
			V _O = V _{CC}		112	150	
			V _O = +12V		137	250	

- Unless otherwise specified min/max limits apply across the -55°C to +180°C temperature range for the DS16F95A. All typical values are given for V_{CC} = 5V and T_A = 25°C.
- All currents into the device pins are positive; all currents out of the device pins are negative. All voltages are referenced to ground unless otherwise specified.
- Δ|V_{OD}| and Δ|V_{OC}| are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.
- In TIA/EIA-422-B and TIA/EIA-485-A Standards, V_{OC}, which is the average of the two output voltages with respect to ground, is called output offset voltage, V_{OS}.
- Refer to TIA/EIA-485-A Standard for exact conditions.
- Only one output at a time should be shorted. Do not exceed maximum junction temperature recommendations. This device does not include thermal shutdown protection.

Driver Switching Characteristics⁽¹⁾

Over recommended supply voltage and operating temperature ranges, unless otherwise specified.

Parameter		Test Conditions		Min	Typ	Max	Units
t _{DD}	Differential Output Delay Time	R _L = 60Ω, Figure 3		8.0	15	45	ns
t _{TD}	Differential Output Transition Time			8.0	15	30	ns
t _{ZH}	Output Enable Time to High Level	R _L = 110Ω, Figure 4			25	50	ns
t _{ZL}	Output Enable Time to Low Level	R _L = 110Ω, Figure 5			25	50	ns
t _{HZ}	Output Disable Time from High Level	R _L = 110Ω, Figure 4			20	80	ns
t _{LZ}	Output Disable Time from Low Level	R _L = 110Ω, Figure 5			20	80	ns
t _{LZL}	Output Disable Time from Low Level with Load Resistor to GND	Load per Figure 4 , Timing per Figure 5			300		ns
t _{SKEW}	Skew (Pulse Width Distortion)	R _L = 60Ω, Figure 3			1.0	12	ns

- Unless otherwise specified min/max limits apply across the -55°C to +180°C temperature range for the DS16F95A. All typical values are given for V_{CC} = 5V and T_A = 25°C.

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Receiver Electrical Characteristics⁽¹⁾⁽²⁾

Over recommended supply voltage and operating temperature ranges, unless otherwise specified.

Parameter		Test Conditions	Min	Typ	Max	Units
V _{TH}	Differential Input High Threshold Voltage	V _O = 2.7V, I _O = -0.4 mA			0.2	V
V _{TL}	Differential Input Low Threshold Voltage ⁽³⁾	V _O = 0.5V, I _O = 2.0 mA	-0.2			V
V _{T+} - V _{T-}	Hysteresis ⁽⁴⁾	V _{CM} = 0V	35	50		mV
V _{IH}	Enable Input Voltage HIGH	\overline{RE}	2.0			V
V _{IL}	Enable Input Voltage LOW				0.8	V
V _{IC}	Enable Input Clamp Voltage	I _I = -18 mA		-0.8	-1.3	V
I _{IH}	Input Current HIGH	V _{IH} = 2.7V		1	20	μA
I _{IL}	Input Current LOW	V _{IL} = 0.4V		-3	-50	μA
V _{OH}	Output Voltage HIGH (RO)	V _{ID} = 200 mV, I _{OH} = -400 μA, Figure 2	2.5	3.5		V
V _{OL}	Output Voltage LOW (RO)	V _{ID} = -200 mV, I _{OL} = 2.0 mA, Figure 2		0.3	0.45	V
I _{OS}	Short Circuit Output Current (RO)	V _O = 0V, (Note 9)	-15	-46	-85	mA
I _{OZ}	High Impedance State Output (RO)	V _O = 0.4V to 2.4V		0.2	±20	μA
I _I	Line Input Current ⁽⁵⁾	A or B, Other Input = 0V		0.57	1.5	mA
		V _I = +12V V _I = -7.0V		-0.43	-0.8	
R _I	Input Resistance	A or B DE = 0.4V	12	18	22	kΩ

- (1) Unless otherwise specified min/max limits apply across the -55°C to +180°C temperature range for the DS16F95A. All typical values are given for V_{CC} = 5V and T_A = 25°C.
- (2) All currents into the device pins are positive; all currents out of the device pins are negative. All voltages are referenced to ground unless otherwise specified.
- (3) The algebraic convention, where the less positive (more negative) limit is designated minimum, is used in this data sheet for common mode input voltage and threshold voltage levels only.
- (4) Hysteresis is the difference between the positive-going input threshold voltage, V_{T+}, and the negative-going input threshold voltage, V_{T-}.
- (5) Refer to TIA/EIA-485-A Standard for exact conditions.

Receiver Switching Characteristics⁽¹⁾

Over recommended supply voltage and operating temperature ranges, unless otherwise specified.

Parameter		Test Conditions	Min	Typ	Max	Units
t _{PLH}	Propagation Delay Time, Low-to-High Level Output	V _{IN} = 0V to +3.0V C _L = 15 pF, Figure 6	10	19	50	ns
t _{PHL}	Propagation Delay Time, High-to-Low Level Output		10	19	50	ns
t _{ZH}	Output Enable Time to High Level	C _L = 15 pF, Figure 7		10	75	ns
t _{ZL}	Output Enable Time to Low Level			12	75	ns
t _{HZ}	Output Disable Time from High Level	C _L = 5.0 pF, Figure 7		12	50	ns
t _{LZ}	Output Disable Time from Low Level			12	50	ns
t _{PLH} - t _{PHL}	Pulse Width Distortion (SKEW)	Figure 6		1.0	16	ns

- (1) Unless otherwise specified min/max limits apply across the -55°C to +180°C temperature range for the DS16F95A. All typical values are given for V_{CC} = 5V and T_A = 25°C.

Device Electrical Characteristics⁽¹⁾⁽²⁾

Over recommended supply voltage and operating temperature ranges, unless otherwise specified.

Parameter		Test Conditions		Min	Typ	Max	Units
I_{CC}	Supply Current (Total Package)	No Load All Inputs Open	DE = 2V, \overline{RE} = 0.8V Outputs Enabled		21.5	28	mA
I_{CCX}			DE = 0.8V, \overline{RE} = 2V Outputs Disabled		16	25	

- (1) Unless otherwise specified min/max limits apply across the -55°C to +180°C temperature range for the DS16F95A. All typical values are given for $V_{CC} = 5V$ and $T_A = 25^\circ C$.
- (2) All currents into the device pins are positive; all currents out of the device pins are negative. All voltages are referenced to ground unless otherwise specified.

Parameter Measurement Information

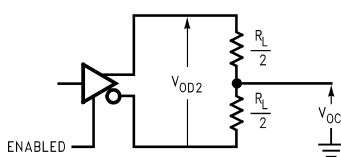


Figure 1. Driver V_{OD} and V_{OC} ⁽³⁾

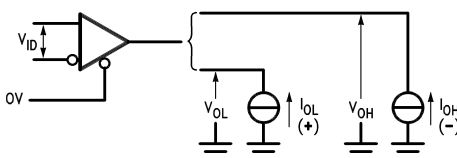
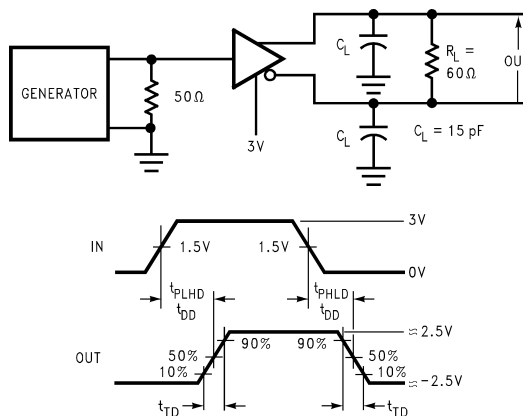


Figure 2. Receiver V_{OH} and V_{OL}



$$t_{SKEW} = |t_{PLHD} - t_{PHLD}|$$

Figure 3. Driver Differential Output Delay and Transition Times⁽⁴⁾⁽⁵⁾

- (3) All diodes are 1N916 or equivalent.
- (4) The input pulse is supplied by a generator having the following characteristics: PRR = 1.0 MHz, 50% duty cycle, $t_r \leq 6.0$ ns, $t_f \leq 6.0$ ns, $Z_O = 50\Omega$.
- (5) DS16F95A Driver enable is Active-High.

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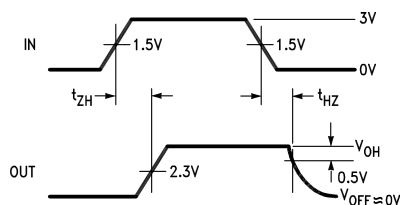
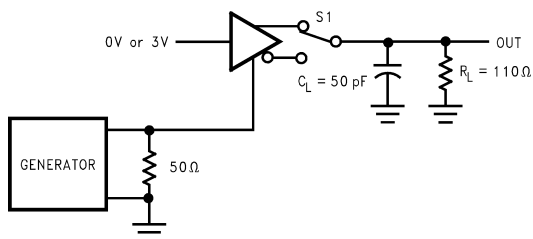


Figure 4. Driver Enable and Disable Times (t_{ZH} , t_{HZ})⁽⁶⁾⁽⁷⁾⁽⁸⁾

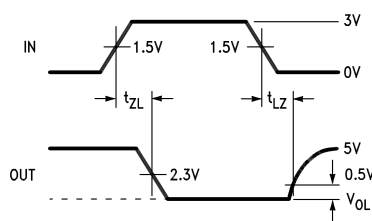
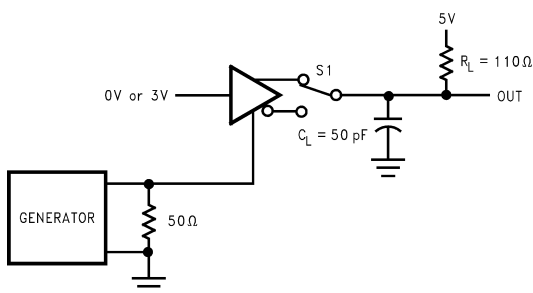


Figure 5. Driver Enable and Disable Times (t_{ZL} , t_{LZ} , t_{LZL})⁽⁶⁾⁽⁷⁾⁽⁸⁾

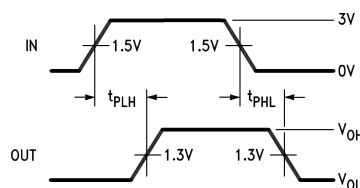
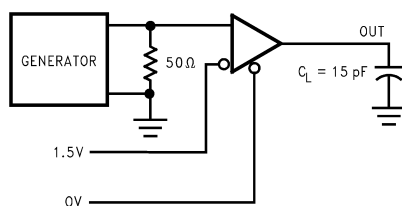


Figure 6. Receiver Propagation Delay Times⁽⁶⁾⁽⁷⁾

- (6) The input pulse is supplied by a generator having the following characteristics: PRR = 1.0 MHz, 50% duty cycle, $t_r \leq 6.0$ ns, $t_f \leq 6.0$ ns, $Z_O = 50\Omega$.
- (7) C_L includes probe and stray capacitance.
- (8) DS16F95A Driver enable is Active-High.

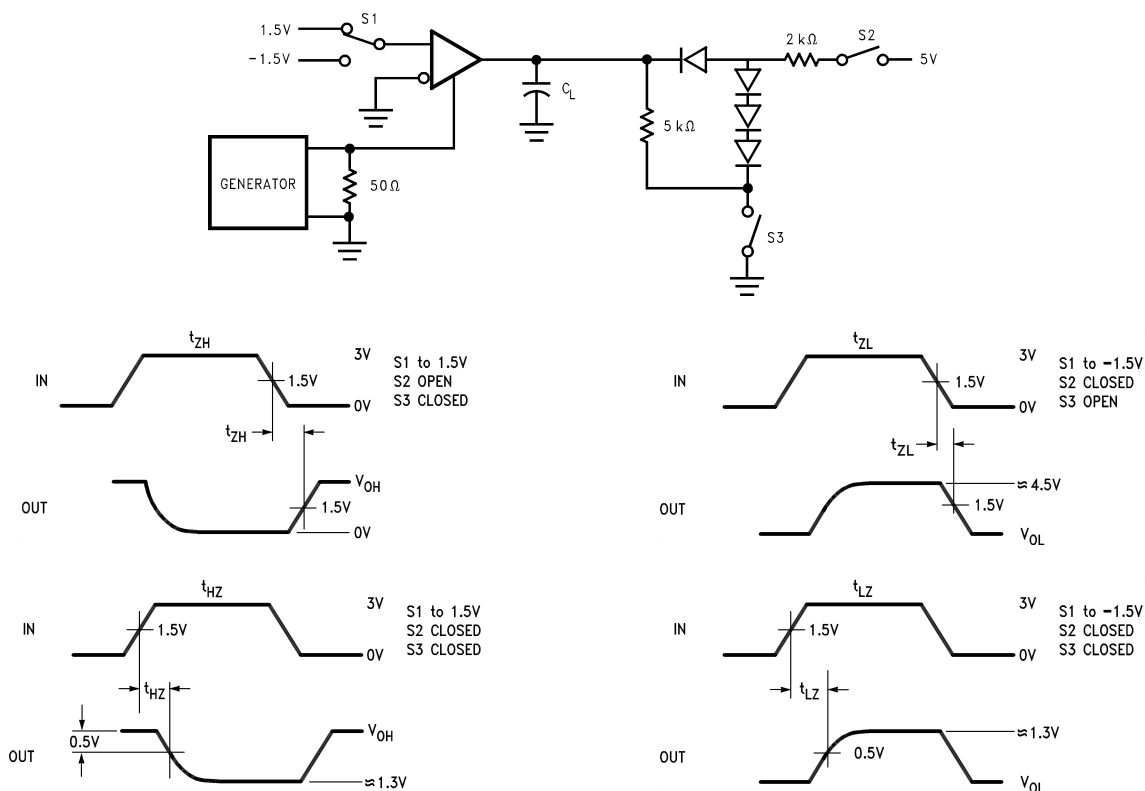


Figure 7. Receiver Enable and Disable Times⁽⁹⁾⁽¹⁰⁾⁽¹¹⁾

- (9) The input pulse is supplied by a generator having the following characteristics: PRR = 1.0 MHz, 50% duty cycle, $t_r \leq 6.0$ ns, $t_f \leq 6.0$ ns, $Z_0 = 50\Omega$.
- (10) C_L includes probe and stray capacitance.
- (11) All diodes are 1N916 or equivalent.

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FUNCTIONAL DESCRIPTION

The Differential Line Driver levels shifts standard TTL/CMOS levels to a differential voltage on the bus pins (A and B) that conform to RS-485. The driver is enabled when the DE pin is High. The driver is disabled when the DE pin is Low. The DI and DE pins should be driven or tied to the desired state, do not float. The differential driver is able to source and sink up to 60mA of output current. Care should be taken that the driver is not enabled into a fault condition where the package power dissipation capacity is exceeded. The DS16F95A features driver current limiting (see I_{OS} specification) to protect from certain line faults where the amount of power is limited. This device is intended for use in rugged applications at elevated temperatures. It does not include a Thermal Shutdown feature commonly found on RS-485 transceivers.

The Differential line Receiver levels shifts the RS-485 levels to standard TTL/CMOS levels. The receiver is enabled when the RE pin is Low. The receiver is disabled when the RE pin is High. The RE pin should be driven or tied to the desired state, do not float.

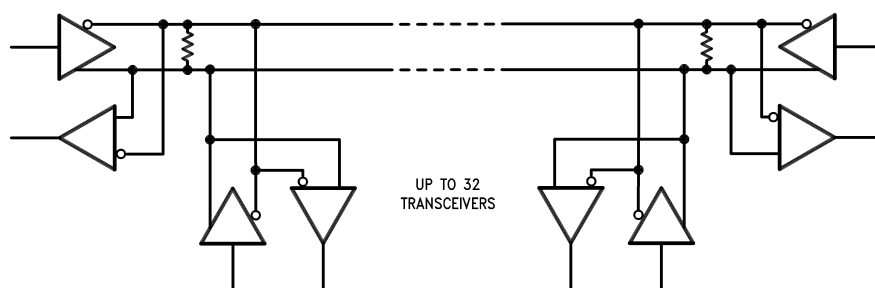
Typical Application

A typical application is shown below. The RS-485 network may be a simple point-to-point connection with two nodes or a more complex one with up to 32 single unit load transceivers as shown above. Stub lengths off the main line should be kept as short as possible to minimize reflections. The line is terminated at both ends in its characteristic impedance (typically 100 or 120 Ohms). The RS-485 network is a bi-directional half duplex interface.

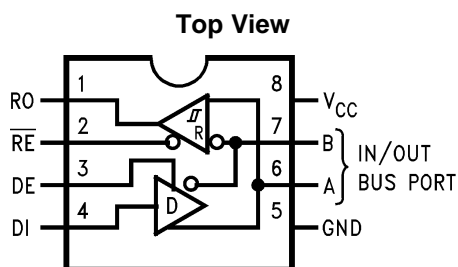
Being a multipoint bus, it is possible for all drivers to be disabled when one or more receivers are enabled. In this case, the receiver(s) is enabled when a valid differential voltage is not present and its output state is unknown. A common solution is to provide external failsafe biasing to bias the line to a known state such that the enabled receives will detect it correctly and idle with a static known state in this condition. See AN-847 (Literature Number [SNLA031](#)) for a discussion on Failsafe biasing of differential buses.

For extended temperature applications, maximum junction temperature should be calculated. $T_{Jmax} = T_A + (\Theta_{JA})(\text{Power Dissipation})$. Θ_{JA} is the reciprocal of the derate term ($1 / 8.7 \text{ mW/}^\circ\text{C}$ or $115 \text{ }^\circ\text{C/W}$). Recommended maximum junction temperature for short duration operation is 200°C. See AN-336 (Literature Number [SNVA509](#)) for a discussion on thermal considerations.

For maximum performance, a few system / PCB recommendations are: drive the logic inputs (DI, DE, RE) with rail-to-rail levels. This will provide the maximum noise margins to the thresholds. A clean supply is also desirable, a 0.1µF capacitor is recommended to be placed near the V_{CC} pin along with a bulk capacitor. The use of power and ground planes is also recommended. Stub lengths off the RS-485 interface should be minimized to limit reflections. Typical interconnect impedance is 100 Ohms.



Connection Diagram



**Figure 8. 8-Lead CDIP Package
 See Package Number NAB0008A**

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REVISION HISTORY

Changes from Revision A (April 2013) to Revision B **Page**

- Changed layout of National Data Sheet to TI format [9](#)



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
DS16F95AJA	ACTIVE	CDIP	NAB	8	40	TBD	Call TI	Call TI	-55 to 180	DS16F95AJA	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

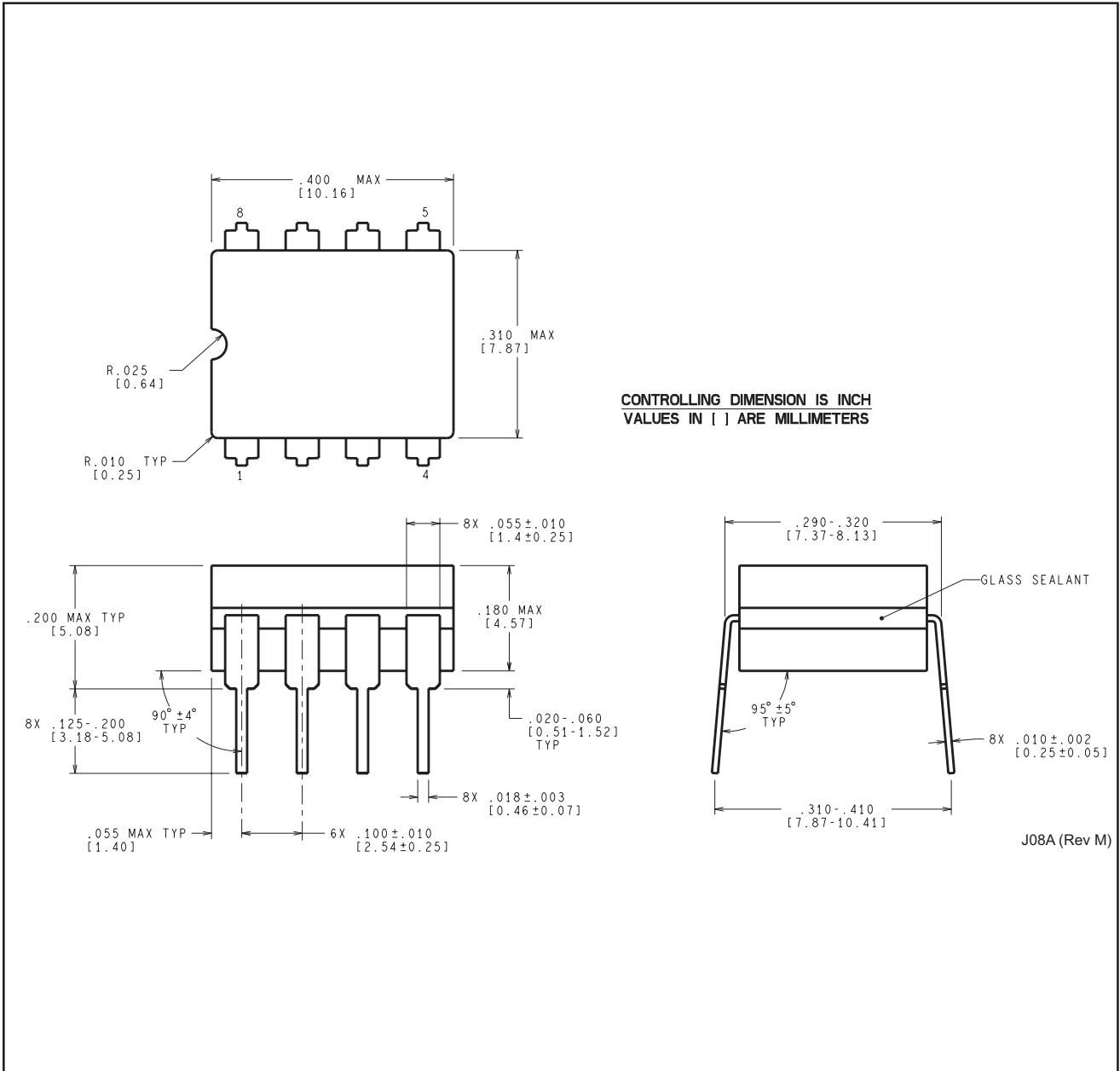
(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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MECHANICAL DATA

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Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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